Processes and process categories	Gas *i*										
	CF_4	C_2F_6	CHF_3	CH_2F_2	C_3F_8	c-C_4F_8	NF_3	SF_6	C_4F_6	C_5F_8	C_4F_8O
PATTERNING/ETCHING											
Oxide etch											
$1-U_i$	0.2-0.8	0.2-0.7	0.2-0.4	0.1-0.8	N/A	0.05-0.3	0.1-0.4	0.1-0.4	0.05-0.3	0.05-0.3	N/A
P_{CF4}	N/A	0.05-0.5	0.005-0.03	0.001-0.01	N/A	0.005-0.1	N/A	N/A	0.02-0.4	0.02-0.4	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	0.005-0.1	N/A	N/A	0.02-0.3	0.02-0.3	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Nitride etch											
$1-U_i$	0.2-0.8	0.2-0.7	0.2-0.4	0.1-0.8	N/A	0.08-0.3	0.1-0.4	0.1-0.4	0.05-0.2	0.05-0.3	N/A
P_{CF4}	N/A	0.05-0.5	0.003-0.1	0.01-0.1	N/A	0.02-0.3	N/A	N/A	0.05-0.4	0.05-0.4	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	0.02-0.3	N/A	N/A	0.05-0.4	0.05-0.4	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Silicon etch											
$1-U_i$	0.2-0.8	0.2-0.7	0.2-0.7	0.02-0.3	N/A	0.1-0.3	0.1-0.4	0.1-0.4	0.05-0.2	0.05-0.3	N/A
P_{CF4}	N/A	0.05-0.5	0.01-0.8	0.05-0.1	N/A	0.01-0.3	N/A	N/A	0.02-0.4	0.02-0.4	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	0.01-0.3	N/A	N/A	0.02-0.3	0.02-0.3	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Metaletch											
$1-U_i$	0.2-0.8	0.2-0.7	0.2-0.7	0.02-0.3	N/A	0.1-0.3	0.1-0.4	0.1-0.4	0.05-0.2	0.05-0.3	N/A
P_{CF4}	N/A	0.05-0.5	0.01-0.8	0.05-0.1	N/A	0.01-0.3	N/A	N/A	0.02-0.4	0.02-0.4	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	0.01-0.3	N/A	N/A	0.02-0.3	0.02-0.3	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
CHAMBER CLEANING											
In situ plasma cleaning											
$1-U_i$	N/A	N/A	N/A	N/A	N/A	N/A	0.1-0.4	N/A	N/A	N/A	N/A
P_{CF4}	N/A	N/A	N/A	N/A	N/A	N/A	0.001-0.6	N/A	N/A	N/A	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A

In situ thermal cleaning											
$1-U_i$	N/A	N/A	N/A	N/A	N/A	N/A	0.002-0.03	N/A	N/A	N/A	N/A
P_{CF4}	N/A	N/A	N/A	N/A	N/A	N/A	0.001-0.05	N/A	N/A	N/A	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
In situ thermal cleaning											
$1-U_i$	N/A	N/A	N/A	N/A	N/A	N/A	0.1-0.4	N/A	N/A	N/A	N/A
P_{CF4}	N/A	N/A	N/A	N/A	N/A	N/A	0.005-.05	N/A	N/A	N/A	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
WAFER CLEANING											
Bevel cleaning											
$1-U_i$	0.3-0.8	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{CF4}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
Ashing											
$1-U_i$	0.3-0.8	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{CF4}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C2F6}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A
P_{C3F8}	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A